

Description

The G3035-23 uses advanced trench technology to provide excellent $R_{DS(ON)}$. This device is suitable for use as a load switch or in PWM applications.

General Features

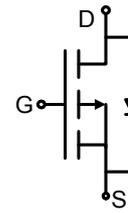
●

| V_{DSS} | $R_{DS(ON)}$ @ -4.5V(Typ) | $R_{DS(ON)}$ @ -10V(Typ) | I_D |
|-----------|------------------------------|-----------------------------|-------|
| -30V | 58m Ω | 40 m Ω | -5 A |

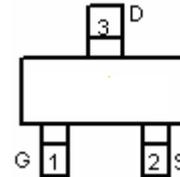
- High power and current handling capability
- Lead free product is acquired
- Surface mount package

Application

- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin assignment



SOT-23

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|----------------|------------|------------------|
| Drain-Source Voltage | V_{DS} | -30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | -5 | A |
| Drain Current-Pulsed ^(Note 1) | I_{DM} | -20 | A |
| Maximum Power Dissipation | P_D | 1.2 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | $^\circ\text{C}$ |

Thermal Characteristic

| | | | |
|---|-----------------|----|--------------------|
| Thermal Resistance, Junction-to-Ambient ^(Note 2) | $R_{\theta JA}$ | 90 | $^\circ\text{C/W}$ |
|---|-----------------|----|--------------------|

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---------------------------------|------------|----------------------------------|-----|-----|-----|---------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=-250\mu\text{A}$ | -30 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=-24V, V_{GS}=0V$ | - | - | -1 | μA |

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|--------------|--|-----|-------|-----------|------------|
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics <small>(Note 3)</small> | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -1 | -1.55 | -3 | V |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}=-10V, I_D=-1A$ | - | 40 | 55 | m Ω |
| | | $V_{GS}=-4.5V, I_D=-1A$ | - | 58 | 85 | m Ω |
| Forward Transconductance | g_{FS} | $V_{DS}=-5V, I_D=-4.1A$ | 5.5 | - | - | S |
| Dynamic Characteristics <small>(Note4)</small> | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=-15V, V_{GS}=0V,$ $F=1.0MHz$ | - | 650 | - | PF |
| Output Capacitance | C_{oss} | | - | 105 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 65 | - | PF |
| Switching Characteristics <small>(Note 4)</small> | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=-15V, R_L=3.6\Omega$ $V_{GS}=-10V, R_{GEN}=3\Omega$ | - | 8.5 | - | nS |
| Turn-on Rise Time | t_r | | - | 4.5 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 26 | - | nS |
| Turn-Off Fall Time | t_f | | - | 12.5 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=-15V, I_D=-4A, V_{GS}=-10V$ | - | 12.5 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 2.8 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 2.7 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage <small>(Note 3)</small> | V_{SD} | $V_{GS}=0V, I_S=-1A$ | - | - | -1.2 | V |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics



Figure 1: Switching Test Circuit

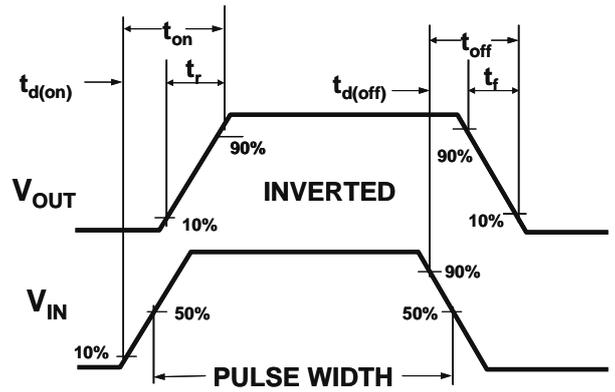


Figure 2: Switching Waveforms

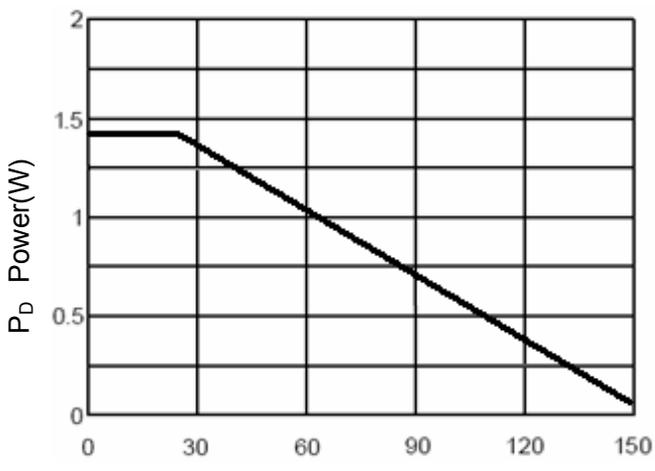


Figure 3 Power Dissipation

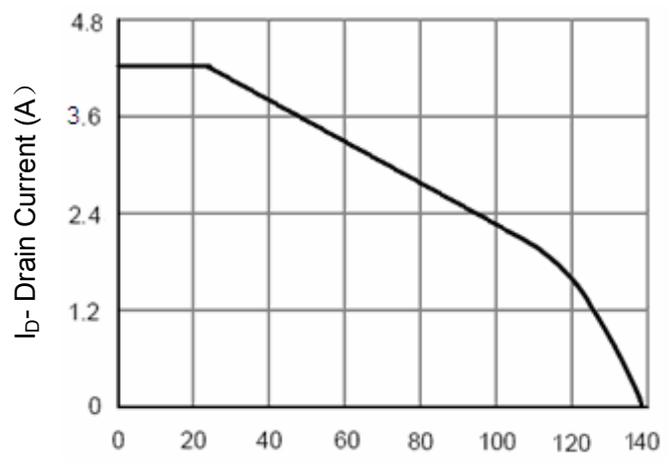


Figure 4 Drain Current

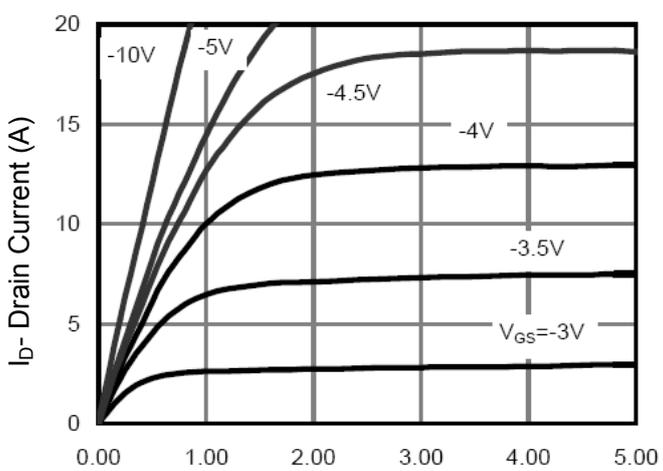


Figure 5 Output Characteristics

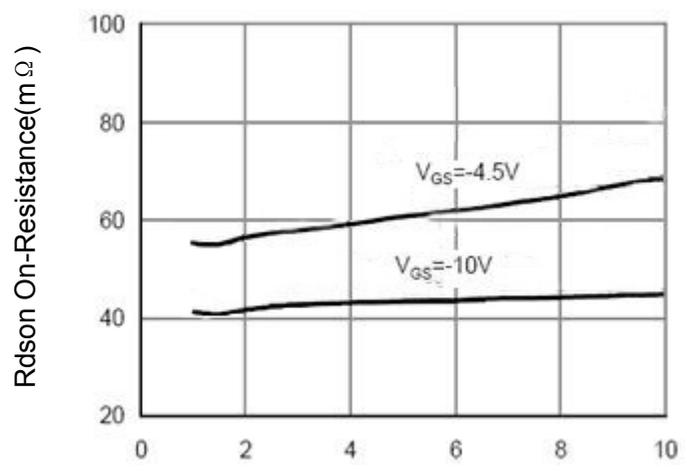


Figure 6 Drain-Source On-Resistance

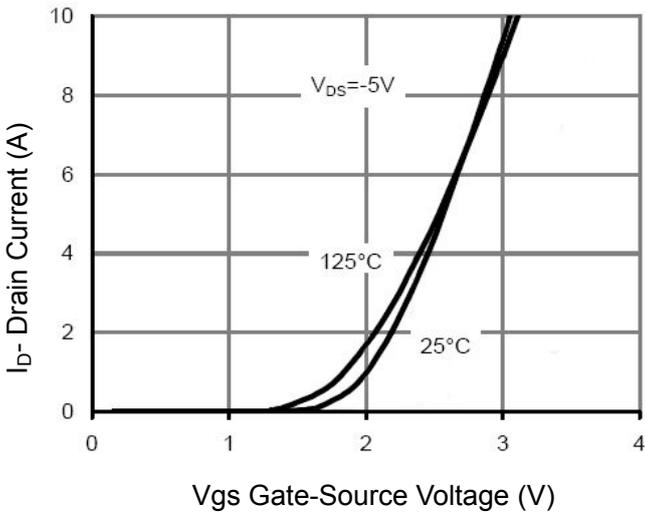


Figure 7 Transfer Characteristics

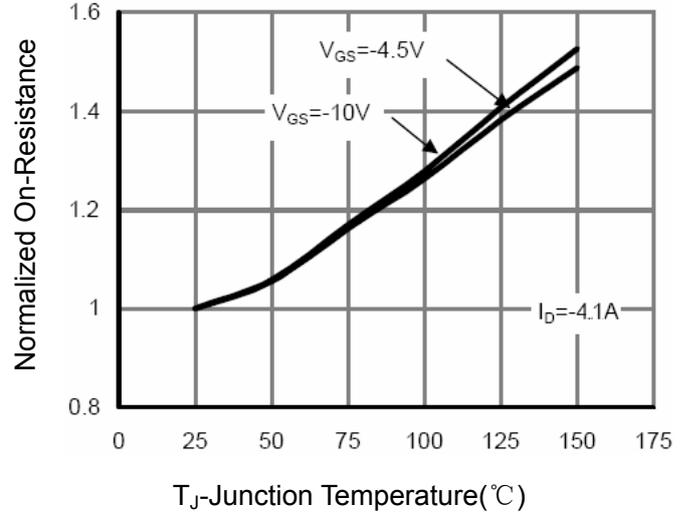


Figure 8 Drain-Source On-Resistance

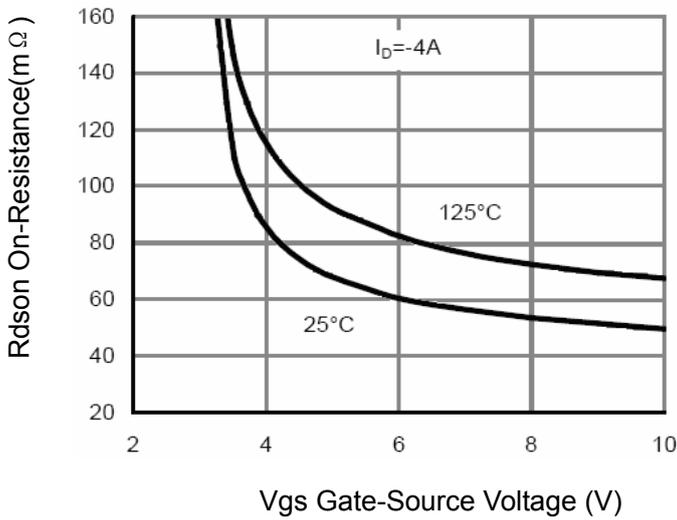


Figure 9 Rdson vs Vgs

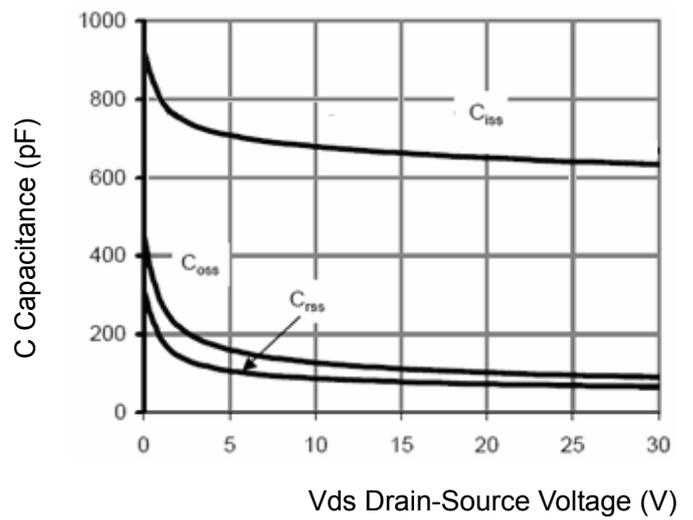


Figure 10 Capacitance vs Vds

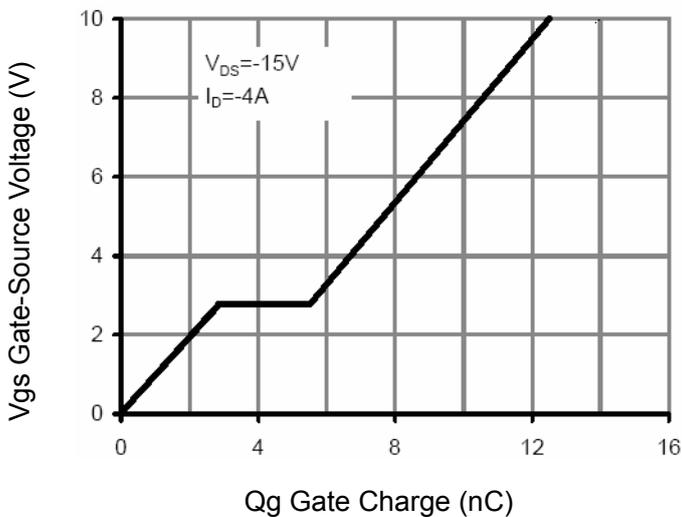


Figure 11 Gate Charge

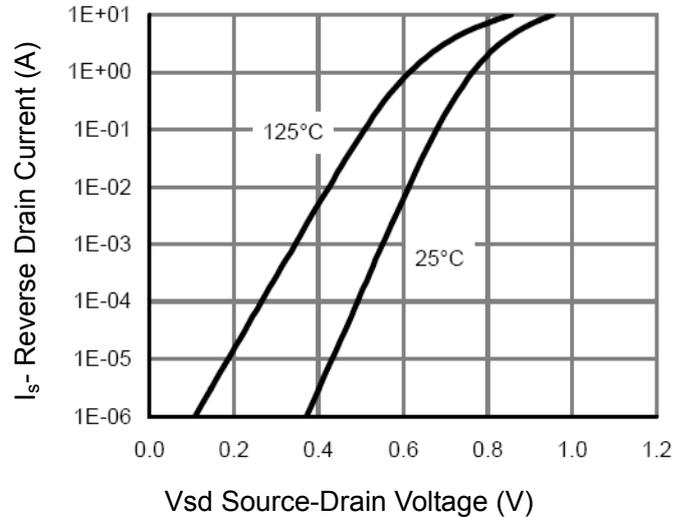


Figure 12 Source- Drain Diode Forward

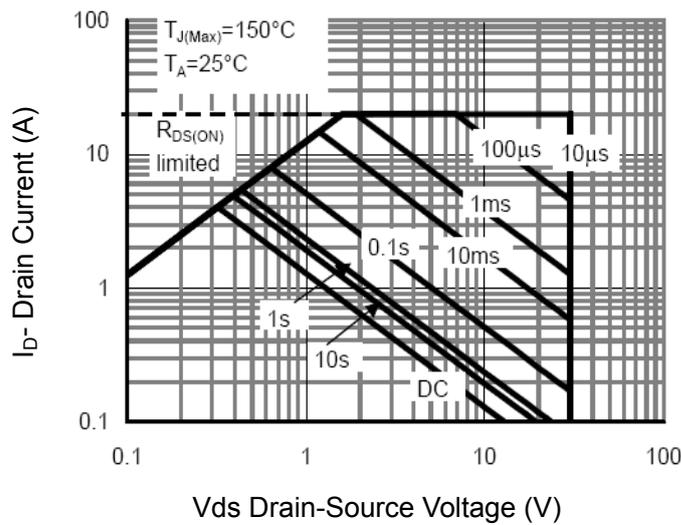


Figure 13 Safe Operation Area

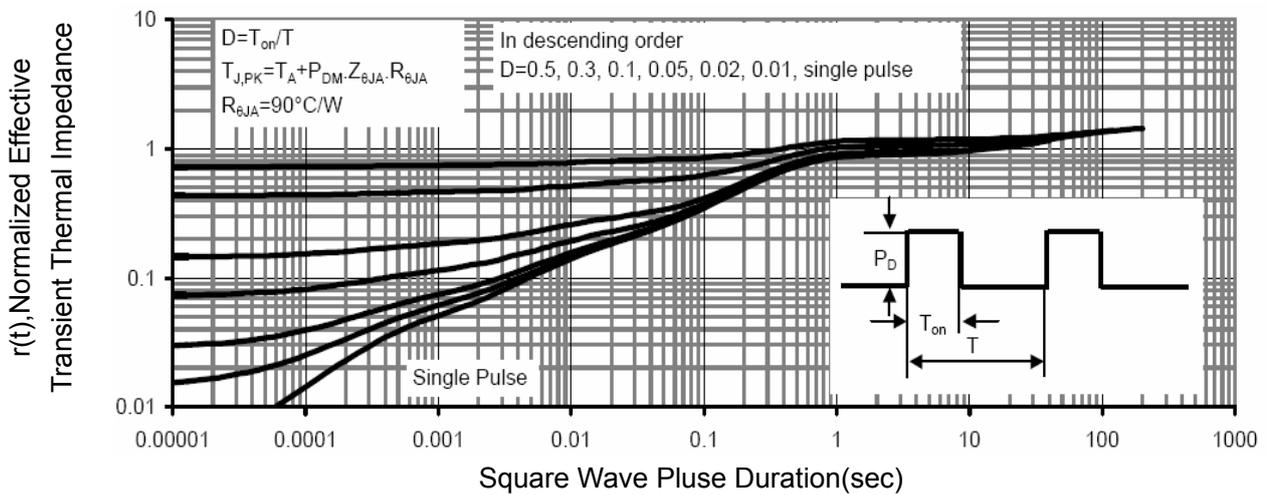


Figure 14 Normalized Maximum Transient Thermal Impedance